Sidewinder is a test handler, based on proven wafer prober technology, for packaged devices in strip or panel format.

Cost of Test and Smaller Package Geometries Create Challenges
Assembly and test costs are approaching and even exceeding wafer fabrication costs for many packaged devices. In addition, the small geometry of new package types is challenging the alignment capabilities of traditional test handling equipment.

Reduce Costs, Increase Throughput
Semiconductor manufacturers and assembly and test providers need to reduce the cost of test while at the same time have capability to handle the even the smallest sizes of chip scale packages (CSP).

A Test Handler with a Prober’s Speed and Accuracy
Sidewinder is a strip test handler that incorporates technologies from our more than 40 years of wafer probe leadership.

The use of prober technology and unique machine vision and handling methodology allow Sidewinder to deliver the fastest possible indexing from strip to strip and from package to package—prober accuracy at speeds faster than any handler.

Our thermal system is designed for optimum throughput. Conductive heat transfer means fast ramp times and the large soak area means no waiting for devices to reach temperature before starting test.

Sidewinder requires only one unique part for package conversion. The rest of the conversion is automatically controlled through software. Even the test contactor can be swapped out without undocking the test head. Sidewinder’s tool-free conversion makes it the most flexible and easiest-to-convert strip handler.

Our range and depth of experience with map-driven processes can ease your transition to a map-driven final test process.

The Next, Easy Step
For more information on how Sidewinder can lower your cost of test and accurately handle your toughest device handling challenges, contact your Electroglas sales representative at (800) 538-5124 or visit www.electroglas.com.
Sidewinder has unmatched throughput.

**Unique strip handling methods allow full tri-temp test capability without affecting throughput – all fully automated.**

---

**ELECTROGLAS, INNOVATIVE TOOLS FOR TEST**

_Electroglas is Focused on Advancing Innovative Technologies to Meet Evolving Challenges in Semiconductor Test._

Test is all about ensuring device quality and manufacturing performance. In the high-volume manufacturing environment of our customers, our innovative products provide substantial value and help lower the overall cost of test.

Electroglas delivers high-speed tools for wafer probing and package test that are reliable, accurate and production proven. Today, we are focused on overcoming our customers’ evolving test challenges, partnering with them to develop solid solutions for wafer probing, prober-based test handling, and test management that will drive greater efficiencies in their wafer and device testing processes. Our customers have rapid, direct access to our worldwide team of experts for service and advice.

**Wafer Probers for Any Test Environment; With Shipments of Over 15,000 Systems**

Electroglas’ probers have been meeting a variety of probing needs for more than 40 years. These automated systems consistently deliver accurate, reliable wafer probing for high volume, low cost manufacturing, as well as leading edge, multi-die, bumped wafer, in-line parametric test and fine-pitch probing applications.

**Prober-Based Test Handlers for Today’s Latest Packaging Technologies**

Electroglas’ test handlers are built upon proven prober technology to give chip-makers a fast, flexible handling solution for today’s final test challenges. Strip test handlers deliver unprecedented throughput for testing a wide variety of popular package types in panel or leadframe format. Filmframe handlers have unique capabilities for testing Wafer Level Packages (WLP), Known Good Die (KGD) on diced wafers, Microelectro-mechanical Systems (MEMS), and ultra-thin wafers.

**Test Floor Management Software for Web-Based Process Analysis and Control**

Electroglas test floor management software provides a unique, networked solution to connect wafer probers and test handlers to the broader testing infrastructure, allowing the chipmaker to better manage overall test effectiveness with accurate and efficient tools for monitoring, analyzing and improving important processes.

**All Products Backed by Global Service for Fastest Response**

Electroglas’ customer service centers are located worldwide for rapid-response field service and local spare parts support. Electroglas demonstrates its commitment to total customer satisfaction through service excellence backed by factory-based technical support, applications development and training.